

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.8	100.0	2.9
			Subtotal	0.8	100	2.9
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.04	100.0	0.14
	Pure metal	Aluminium (Al)	7429-90-5	0.16	100.0	0.56
			Subtotal	0.2	200	0.7
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01	2.0	0.05
	Lead alloy	Silver (Ag)	7440-22-4	0.02	2.5	0.07
	Lead alloy	Lead (Pb)	7439-92-1	0.72	95.5	2.58
			Subtotal	0.75	100	2.7
Post-plating	Pure metal	Tin (Sn)	7440-31-5	4.43	100.0	16
			Subtotal	4.43	100	16
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.05
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01	0.03	0.05
	Copper alloy	Iron (Fe)	7439-89-6	0.05	0.1	0.18
	Copper alloy	Copper (Cu)	7440-50-8	49.12	99.84	177.32
			Subtotal	49.19	100	177.6
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.79	4.0	6.44
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.69	15.0	24.16
	Filler	Silica fused	60676-86-0	33.02	74.0	119.21
	Flame retardant	Metal hydroxide		3.12	7.0	11.28
			Subtotal	44.62	100	161.09
			Total	99.99	100	360.99

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